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# **PRODUCT CHANGE NOTICE**

**Alternate Manufacturing Site  
for Assembly of the Listed  
Intersil QFN Packaged  
Products**

**Refer to:  
PCN12052**

**Date: July 12, 2012**

July 12, 2012

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of the Listed Intersil QFN Packaged Products – Advanced Semiconductor Engineering - Chung-Li, Taiwan (ASECL)**

This notice is to inform you that Intersil will begin using the Advanced Semiconductor Engineering (ASECL) facility as alternate site for assembly of the listed QFN (Quad Flat No-Lead) packaged products. Products manufactured at the ASECL facility will be assembled using copper bond wire as an alternate to the gold wire currently used today. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep, and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. As of this notice, the product and site-specific qualification activities are complete.

Products affected:

ISL6228HRTZ    ISL62882CHRTZ    ISL62883CHRTZ    ISL95870BHRZ  
ISL6228HRTZ-T    ISL62882CHRTZ-T    ISL62883CHRTZ-T    ISL95870BHRZ-T

The Advanced Semiconductor Engineering (ASECL) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly of QFN packaged products with both copper and gold bond wire material. There will be no change in the mold compound series (G770), die attach, lead frame material, or package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260 °C per J-STD-020). As such, the listed products will be packed, labeled, and shipped as moisture sensitivity level three (MSL 3) upon implementation of the changes outlined in this PCN. The qualified material set combinations for assembly are as follows:

Key Items	CAS Current	ASECL New (Alternate)
Mold Compound	Sumitomo EME-G770HC	Sumitomo EME-G770HJ
Die Attach	Hysol QMI 519	Hysol QMI 519
Bond Wire	1.0 mil Gold	1.0 mil Copper (CU) w/ Palladium (Pd) Coat
Moisture Sensitivity Level	1 ,2, 3	3
Device Marking - Site Code	F	W

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ASECL may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at ASECL with copper bond wire is "W".

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Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

*Jon Brewster*

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Intersil Corporation

PCN12052

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## PCN12052 – ASECL Reliability Qualification Summary

Test Name	Product	Package	Precon.	Lots	Sample Size	Condition	Duration	Rejects
HAST MONITOR	ISL88731CHRTZ-T	28 LEAD 5X5 TQFN	L3 PBFREE	238	40,001	130C, 85%RH	48	0
HAST MONITOR	ISL88731CHRTZ-T	28 LEAD 5X5 TQFN	L3 PBFREE	3	5,444	130C, 85%RH	96	0
HAST UNBIAS	ISL88731CHRTZ	28 LEAD 5X5 TQFN	L3 PBFREE	10	10946	130C, 85%RH	96	0
TEMP CYCLE	ISL88731CHRTZ	28 LEAD 5X5 TQFN	L3 PBFREE	1	238	-40C TO 125C	1000	0
TEMP CYCLE	ISL88731CHRTZ	28 LEAD 5X5 TQFN	L3 PBFREE	5	225	-65C TO 150C	500	0
STORAGE	ISL88731CHRTZ	28 LEAD 5X5 TQFN	L3 PBFREE	4	180	150C	1000	0
MRT LEVEL 3	ISL88731CHRTZ	28 LEAD 5X5 TQFN	L3 PBFREE	1	22	30C, 60%RH	192	0

Test Name	Product	Package	Precon.	Lots	Sample Size	Condition	Duration	Rejects
HAST MONITOR	ISL6267HRZ-T	48 LEAD 6X6 TQFN	L3 PBFREE	2	270	130C, 85%RH	48	0
HAST UNBIAS	ISL6267HRZ	48 LEAD 6X6 TQFN	L3 PBFREE	1	78	130C, 85%RH	96	0
HTOL	ISL6267HRZ	48 LEAD 6X6 TQFN		1	76	125C	1000	0
TEMP CYCLE	ISL6267HRZ	48 LEAD 6X6 TQFN	L3 PBFREE	1	78	-40C TO 125C	1000	0
MRT LEVEL 3	ISL6267HRZ	48 LEAD 6X6 TQFN	L3 PBFREE	1	22	30C, 60%RH	192	0